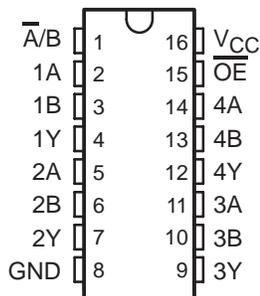


SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

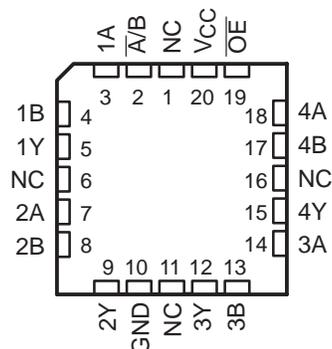
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- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State Outputs Interface Directly With System Bus
- Typical $t_{pd} = 17$ ns
- Low Power Consumption, 80- μ A Max I_{CC}
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Inputs Are TTL-Voltage Compatible
- Provide Bus Interface From Multiple Sources in High-Performance Systems
- Buffered Inputs and Outputs

SN54HCT257 . . . J PACKAGE
SN74HCT257 . . . D OR N PACKAGE
(TOP VIEW)



SN54HCT257 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HCT257 devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{OE}) input is at the high logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HCT257N	SN74HCT257N
	SOIC – D	Tube of 40	SN74HCT257D	HCT257
		Reel of 2500	SN74HCT257DR	
		Reel of 250	SN74HCT257DT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HCT257J	SNJ54HCT257J
	LCCC – FK	Tube of 55	SNJ54HCT257FK	SNJ54HCT257FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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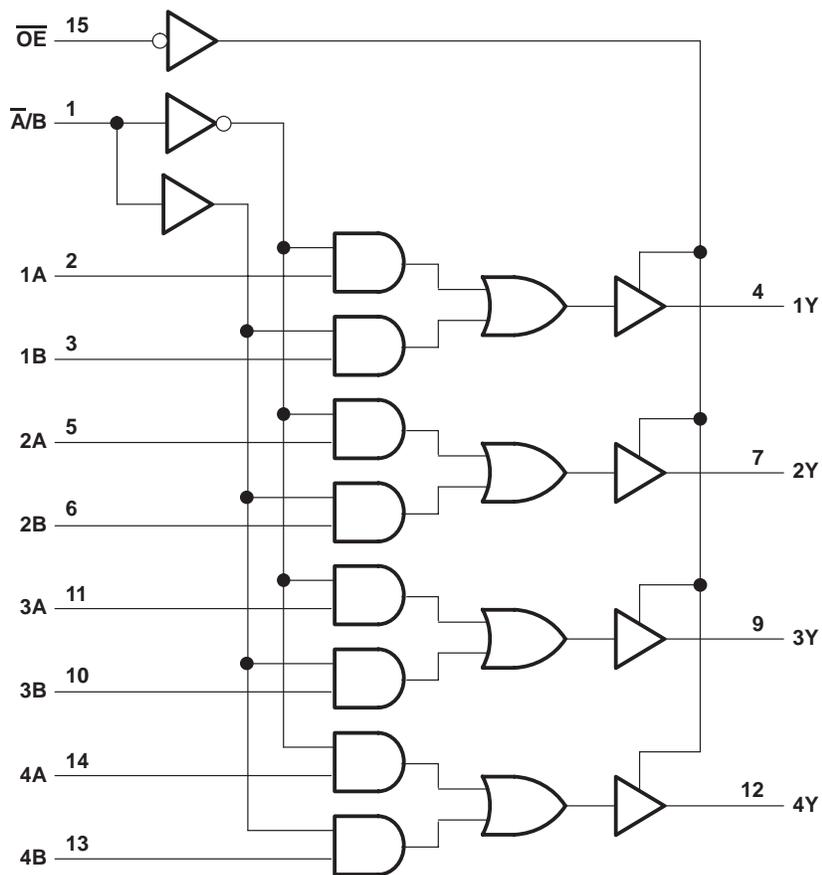
SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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FUNCTION TABLE

\overline{OE}	INPUTS		OUTPUT Y	
	SELECT $\overline{A/B}$	DATA		
		A		B
H	X	X	X	
L	L	L	L	
L	L	H	H	
L	H	X	L	
L	H	X	H	

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 35 mA
Continuous current through V_{CC} or GND	± 70 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
N package	67°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54HCT257			SN74HCT257			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 4.5$ V to 5.5 V		2	2			V
V_{IL}	Low-level input voltage	$V_{CC} = 4.5$ V to 5.5 V			0.8			V
V_I	Input voltage	0	V_{CC}		0	V_{CC}		V
V_O	Output voltage	0	V_{CC}		0	V_{CC}		V
t_t	Input transition (rise and fall) time		500			500		ns
T_A	Operating free-air temperature	-55	125		-40	85		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HCT257		SN74HCT257		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL}	4.5 V	$I_{OH} = -20 \mu\text{A}$		4.4	4.499	4.4	4.4	V	
			$I_{OH} = -6 \text{ mA}$		3.98	4.3	3.7	3.84		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	4.5 V	$I_{OL} = 20 \mu\text{A}$			0.001	0.1	0.1	V	
			$I_{OL} = 6 \text{ mA}$			0.17	0.26	0.4		0.33
I_I	$V_I = V_{CC}$ or 0	5.5 V		± 0.1	± 100	± 1000	± 1000	nA		
I_{OZ}	$V_O = V_{CC}$ or 0, $V_I = V_{IH}$ or V_{IL}	5.5 V		± 0.01	± 0.5	± 10	± 5	μA		
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$	5.5 V			8	160	80	μA		
ΔI_{CC}^\ddagger	One input at 0.5 V or 2.4 V, Other inputs at 0 or V_{CC}	5.5 V		1.4	2.4	3	2.9	mA		
C_i		4.5 V to 5.5 V		3	10	10*	10	pF		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC} .

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SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HCT257		SN74HCT257		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	4.5 V		20	30		45		38	ns
			5.5 V		17	27		40		34	
	\bar{A}/B	Y	4.5 V		20	30		45		38	
			5.5 V		17	27		40		34	
t_{en}	\overline{OE}	Y	4.5 V		20	30		45		38	ns
			5.5 V		17	27		40		34	
t_{dis}	\overline{OE}	Y	4.5 V		20	30		45		38	ns
			5.5 V		17	27		40		34	
t_t		Any	4.5 V		8	15		22		19	ns
			5.5 V		7	14		21		17	

switching characteristics over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HCT257		SN74HCT257		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	4.5 V		22	38		57		48	ns
			5.5 V		19	35		53		44	
	\bar{A}/B	Y	4.5 V		22	38		57		48	
			5.5 V		19	35		53		44	
t_{en}	\overline{OE}	Y	4.5 V		23	40		60		50	ns
			5.5 V		20	38		57		48	
t_t		Any	4.5 V		17	42		63		53	ns
			5.5 V		14	38		57		48	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	13	pF

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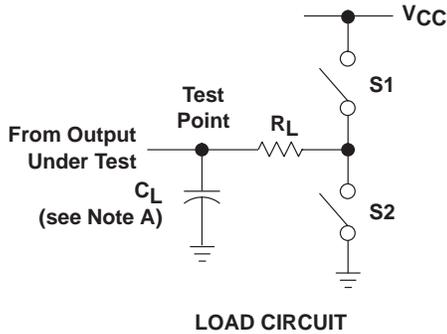


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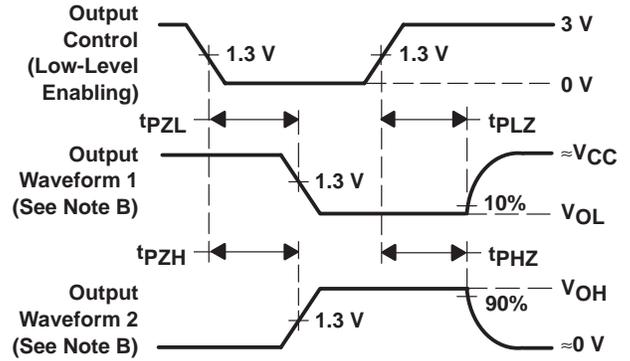
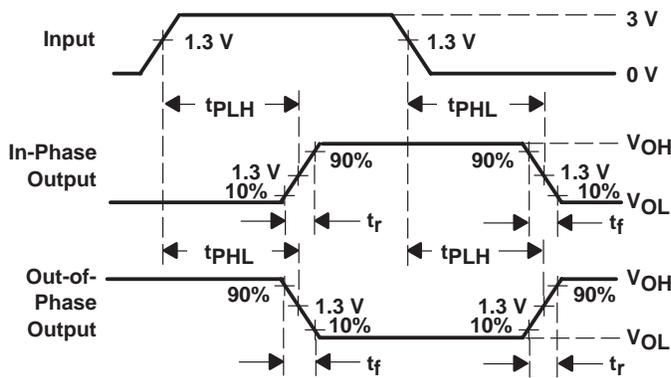
SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION



PARAMETER		R_L	C_L	S1	S2
t_{en}	t_{PZH}	1 k Ω	50 pF or 150 pF	Open	Closed
	t_{PZL}			Closed	Open
t_{dis}	t_{PHZ}	1 k Ω	50 pF	Open	Closed
	t_{PLZ}			Closed	Open
t_{pd} or t_t		--	50 pF or 150 pF	Open	Open



- NOTES:
- A. C_L includes probe and test-fixtue capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HCT257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HCT257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

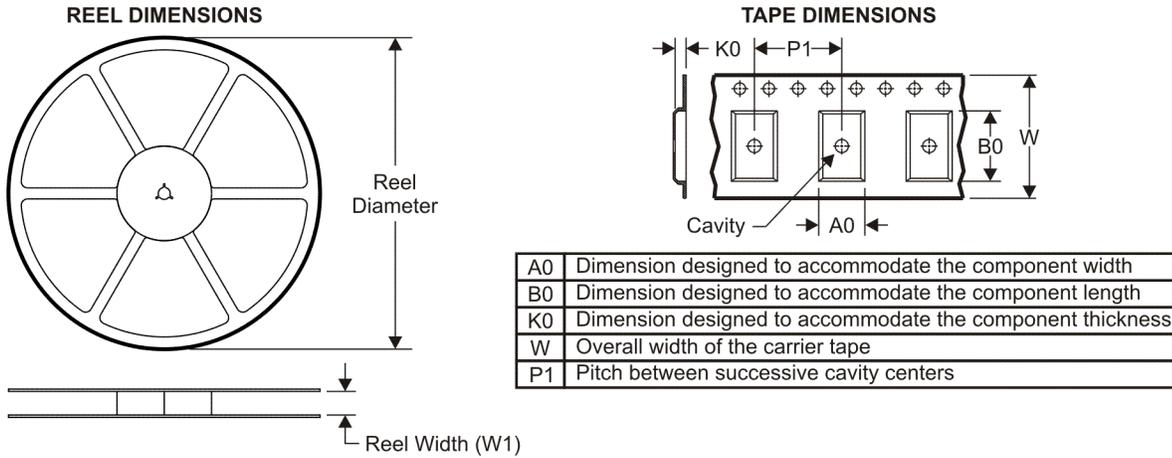
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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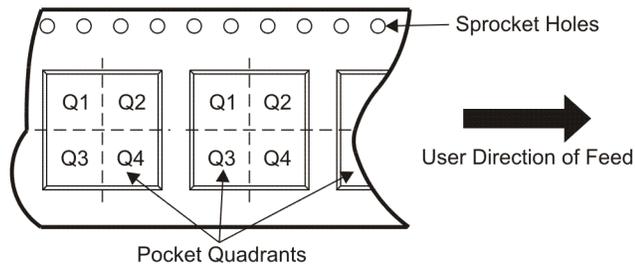
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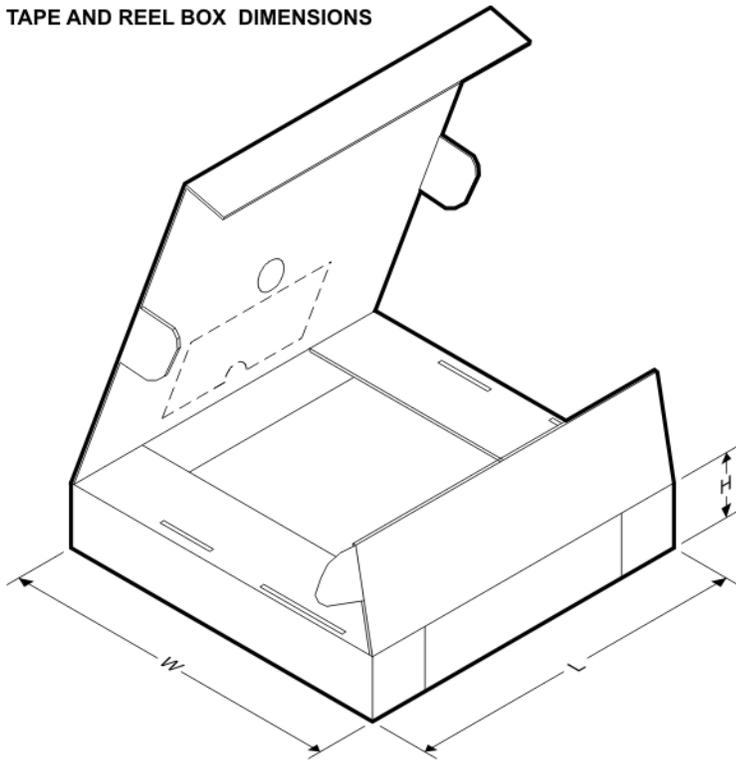
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT257DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



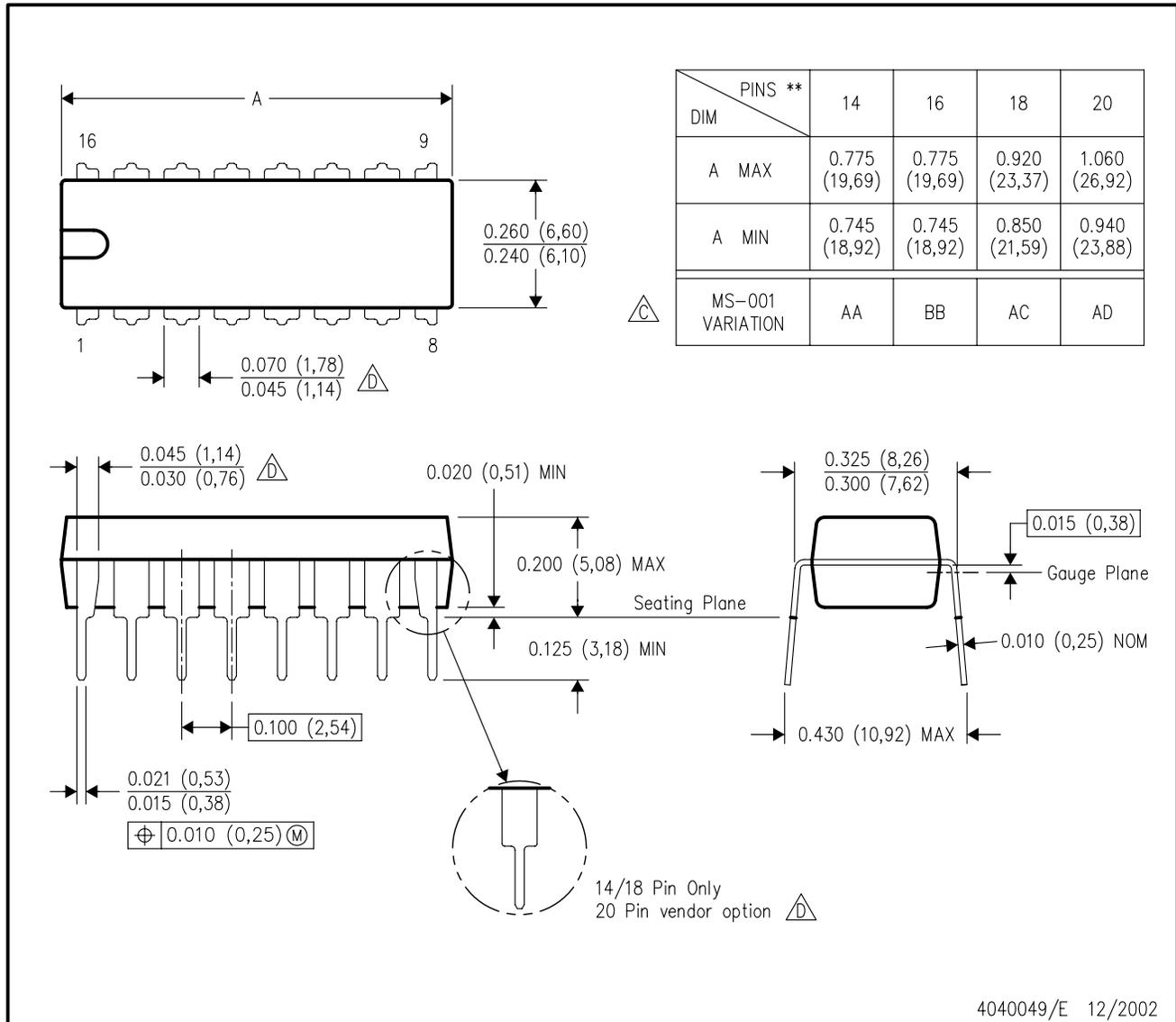
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT257DR	SOIC	D	16	2500	333.2	345.9	28.6

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

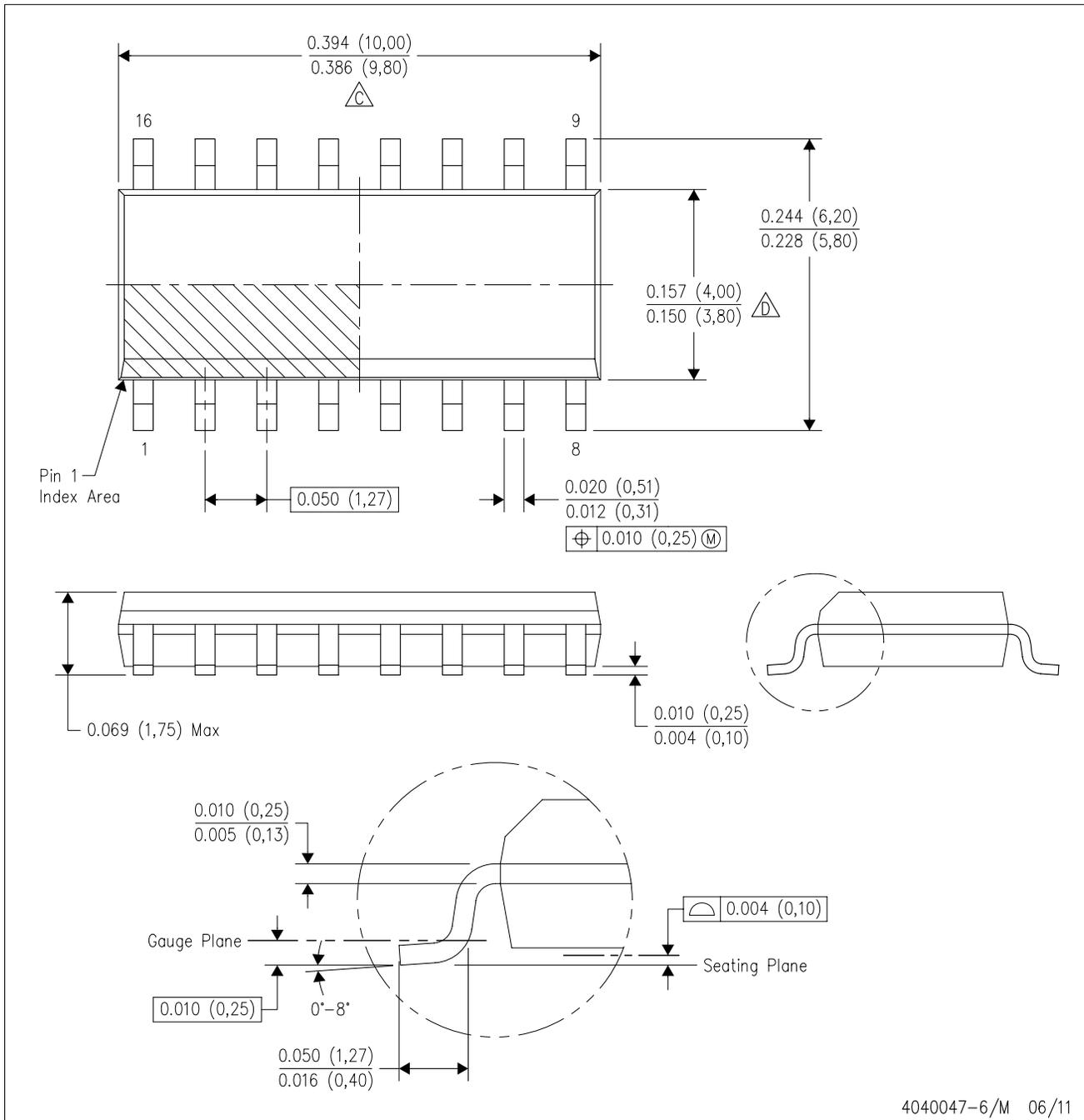
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

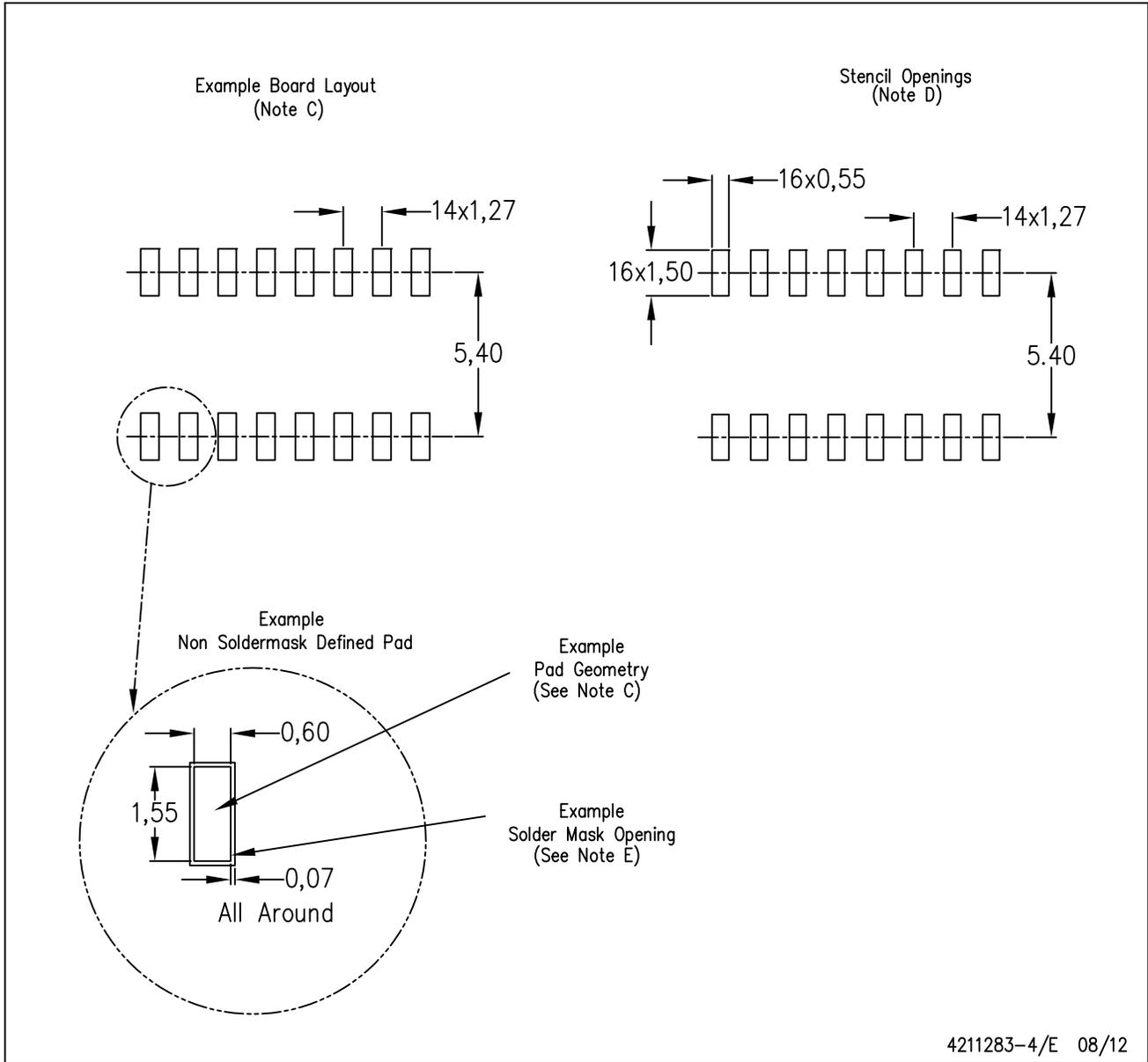
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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